Title (en)

JUNCTION BETWEEN A MICROSTRIP LINE AND A WAVEGUIDE

Title (de)

ÜBERGANG ZWISCHEN EINER MIKROSTREIFENLEITUNG UND EINEM HOHLLEITER

Title (fr)

JONCTION ENTRE UNE MICROBANDE ET UN GUIDE D'ONDES

Publication

EP 1540762 A1 20050615 (DE)

Application

EP 03798047 A 20030730

Priority

- DE 0302553 W 20030730
- DE 10243671 A 20020920

Abstract (en)

[origin: US2006145777A1] An arrangement for a junction between a microstripline and a waveguide is provided. The arrangement includes a microstripline fitted on the upper face of a dielectric substrate, a waveguide fitted on the upper face of the substrate and has an opening on at least one end surface and has a structure which is in the form of a step or steps in the area of the opening on one side wall and is conductively connected in at least one part to a microstripline. One side wall of the waveguide is a metallized layer formed on the substrate. A cutout is formed in the metallized layer and into which the microstripline projects. A rear-face metallization is formed on the rear face of the substrate, and electrically conductive via holes between the metallized layer on the upper face of the substrate and the rear-face metallization, which surround the cutout.

IPC 1-7

H01P 5/107

IPC 8 full level

H01P 5/107 (2006.01)

CPC (source: EP KR US)

H01P 5/107 (2013.01 - EP KR US)

Citation (search report)

See references of WO 2004030142A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

US 2006145777 A1 20060706; **US 7336141 B2 20080226**; AT E406672 T1 20080915; AU 2003257396 A1 20040419; AU 2003257396 B2 20080925; BR 0306449 A 20041026; CA 2499585 A1 20040408; CA 2499585 C 20110215; CN 100391045 C 20080528; CN 1682404 A 20051012; DE 10243671 B3 20040325; DE 50310414 D1 20081009; EP 1540762 A1 20050615; EP 1540762 B1 20080827; ES 2312850 T3 20090301; IL 167325 A 20100415; JP 2005539461 A 20051222; JP 4145876 B2 20080903; KR 100958790 B1 20100518; KR 20050057509 A 20050616; NO 20041694 L 20040427; PL 207180 B1 20101130; PL 374171 A1 20051003; WO 2004030142 A1 20040408

DOCDB simple family (application)

US 52843105 A 20051215; AT 03798047 T 20030730; AU 2003257396 A 20030730; BR 0306449 A 20030730; CA 2499585 A 20030730; CN 03822218 A 20030730; DE 0302553 W 20030730; DE 10243671 A 20020920; DE 50310414 T 20030730; EP 03798047 A 20030730; ES 03798047 T 20030730; IL 16732505 A 20050308; JP 2004538686 A 20030730; KR 20057004819 A 20030730; NO 20041694 A 20040427; PL 37417103 A 20030730